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the	attached	original	documents	or

To the Honorable Commissioner of Paten copy thereof.

102320864

1. Name of Conveying party(ies): Larry Clevenger, Timothy J. Dalton, Steffen K. Kaldor, Kaushik Kumar, Douglas C. La Tulipe, Jr., Soon-Cheon Seo, Andrew H. Simon, Yun-Yu Wang, Chih-Chao Yang, Haining Yang

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2. Name & address of receiving party(ies)

Name: International Business Machines Corporation

Street

Address:

New Orchard Road

City: Armonk State: New York ZIP: 10504

4. Application number(s) or patent number(s):

Title of Application: A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE **HAVING A CAPPING LAYER**

If this document is being filed together with a new application, the execution date of the application is: 12/10/02, 12/06/02, 11/22/02, 12/03/02, 12/06/02, 11/22/02, 11/25/02, 11/22/02, 11/26/02, 12/03/02.

Patent Application No(s). Docket No.

Serial No.

B. Patent No(s)

10/318606

Additional numbers attached? ___Yes _X_No

Name and address of party to whom correspondence concerning document should be mailed:

Name: Ira D. Blecker

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PATENT TRADEMARK OFFICE

IBM Corporation Intellectual Property Law Dept. Dept. 18G/Bldg. 300-482 2070 Route 52

Hopewell Junction, NY 12533-6531

patents involved: 1

6. Total number of applications and

7. Total fee (37 CFR 3.41): \$40.00 _ Enclosed

X Authorized to be charged to deposit account

Deposit A/C no.: 09-0458 (FI-565) (Attach duplicate copy of this page if paying by deposit account)

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9. Statement of signature:

To the best of my knowledge and belief I the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ira D. Blecker, Reg. No. 29,894

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Telephone No. (845) 894-2580

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December 11, 2002 DATE OF DEPOSIT

KAREN CINQ-MARS

REEL: 013594 FRAME: 0444

ASSIGNMENT

WHEREAS, we

(1) Larry Clevenger	of LaGrangeville
County of Dutchess	State of New York
and	
(2) Timothy J. Dalton	of Ridgefield
County of Fairfield	State of New York
and	
(3) Steffen K. Kaldor	of New York
County of New York	State of New York
and	
(4) Kaushik Kumar	of Beacon
County of Dutchess	State of New York
and	
(5) Douglas C. La Tulipe, Jr.	of Danbury
County of Fairfield	State of New York
and	
(6) Soon-Cheon Seo	of White Plains
County of Westchester	State of New York
and	
(7) Andrew H. Simon	of Fishkill
County of Dutchess	State of New York
and	
(8) Yun-Yu Wang	of Poughquag
County of Dutchess	State of New York
and	
(9) Chih-Chao Yang	of Beacon
County of Dutchess	State of New York
and	
(10) Haining Yang	of Wappingers Falls
County of Dutchess	State of New York

have invented certain improvements in

A METHOD FOR DEPOSITING A METAL LAYER ON A SEMICONDUCTOR INTERCONNECT STRUCTURE HAVING A CAPPING LAYER

Page 1 of 3 PATENT REEL: 013594 FRAME: 0445 and executed a United States patent application therefor on: (dates that Inventors signed the declaration)

(1)
$$\frac{12/14/62}{12/66}$$
, and (2) $\frac{12/06/02}{02}$, and (3) $\frac{11/22/2002}{2002}$, and (4) $\frac{12/03/2002}{2002}$

(5)
$$\frac{12/6/02}{10^2}$$
, and (6) $\frac{11/22/2007}{2007}$, and (7) $\frac{11/75/2007}{2007}$, and (8) $\frac{11/22/02}{2007}$

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire, right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

(1) at 2/10/02 on East Fishill NY

Larry Clevenger

(2) at 12/6/02 on East Fyhk.ll, My,

Timothy J. Dalton

REEL: 013594 FRAME: 0446

(3) at	E. FishKill, NY
on	11/22/02

Stoffen K. Kalder

(4) at & Fishkill, NY on 12/03/02, Alanh.

(5) at \(\varphi\). Fishkil, NY on \(\frac{17/06/02}{}\),

Douglas C. La Tulipe, Jr.

6) at & fishkill, NY on (1/22/02).

Douglas C. La Tampe, of

(7) at E. Fishkil, NY

Soon-Cheon Seo

on 11/25/02,

Andrew H. Simon

(8) at Fishill, NY on 11-22-02

Yun-Yu Wang

(9) at E. Fishkill, NY on Nov. 2602,

Chih-Chao Yang

(10) at E. Fishhill, Nij on 12/03/02,

RECORDED: 12/11/2002

Halming Yang

PATENT 3 of 3

REEL: 013594 FRAME: 0447